

IN THE SPECIFICATION

Please amend the paragraphs at page 25, lines 20-24, as follows:

Fig. 4 is a flow chart for explaining the embodiment of a device manufacturing method according to the present invention; [[and]]

Fig. 5 is a flow chart showing processing in step 204 of Fig. 4; and

Fig. 6 is a view schematically showing the entire structure and arrangement of the exposure apparatus.

Please amend the paragraph at page 28, lines 10-27, as follows:

Each of the exposure chamber 16, the reticle loader chamber 18 and the wafer loader chamber 20 is connected to the machine chamber 14 via a supply duct 24, which is made of a material emitting less gass such as stainless steel (SUS), Teflon (a registered trademark) or the like, and a connection unit 26 connected to the opposite end portion of the supply duct 24 from the exposure chamber 16, the reticle loader chamber 18 and the wafer loader chamber 20. The connection unit 26 is detachable at least from the supply duct 24 (main body chamber 12), and is constituted by an expandable and contractible bellows-like member in this case. Accordingly in this embodiment, vibration generated by the blower constituting the air conditioner (described later) housed inside the machine chamber 14 is absorbed by expansion of the connection unit 26, and influence that the vibration gives to the main body chamber 12 is efficiently reduced. Note that the supply duct 24 and the connection unit 26 constitute the supply path in this embodiment. In addition, the machine chamber 14 may be